

Precision, High Speed Operational Amplifier

DESCRIPTION

The **RH[®]118** is a precision, high speed operational amplifier which offers wide bandwidth and high slew rate. Unlike many wideband amplifiers, the RH118 is unity-gain stable and has a slew rate of 50V/μs.

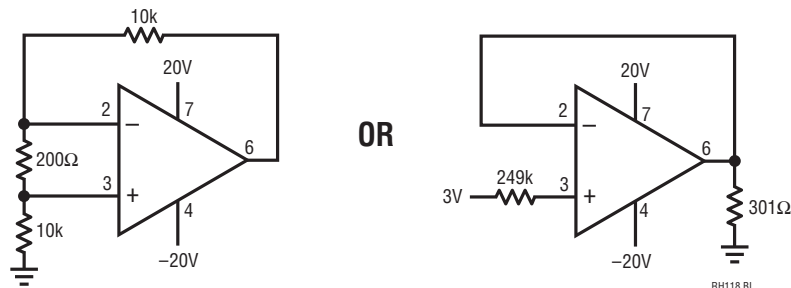
The wafer lots are processed to Analog Devices' in-house Class S flow to yield circuits usable in stringent military applications.

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ABSOLUTE MAXIMUM RATINGS

Supply Voltage	±20V
Differential Input Current (Note 1).....	±10mA
Input Voltage (Note 2)	±20V
Output Short-Circuit Duration	Indefinite
Operating Temperature Range	–55°C to 125°C
Storage Temperature Range	–65°C to 150°C
Lead Temperature (Soldering, 10 sec).....	300°C

BURN-IN CIRCUIT (Each Amplifier)



PACKAGE/ORDER INFORMATION

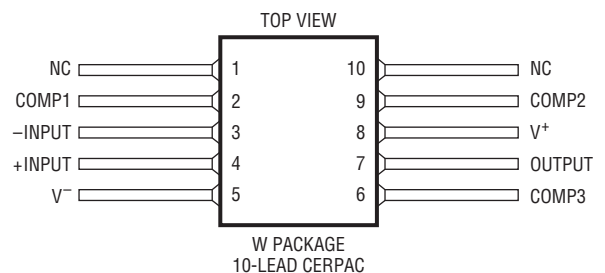
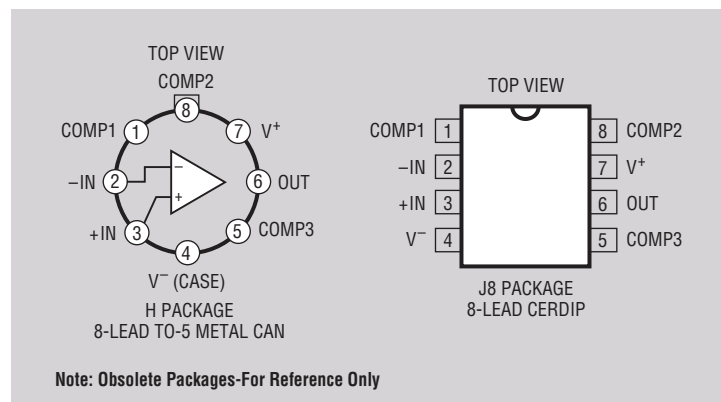


TABLE 1: ELECTRICAL CHARACTERISTICS (Preirradiation) (Note 3)

Device is characterized at the TID levels below. Device is production tested at 100kRad(Si).

SYMBOL	PARAMETER	CONDITIONS	NOTES	T _A = 25°C			SUB-GROUP	-55°C ≤ T _A ≤ 125°C			SUB-GROUP	UNITS
				MIN	TYP	MAX		MIN	TYP	MAX		
V _{OS}	Input Offset Voltage					4	1			6	2,3	mV
I _{OS}	Input Offset Current					50	1			100	2,3	nA
I _B	Input Bias Current					250	1			500	2,3	nA
R _{IN}	Input resistance		4	1								MΩ
A _V	Large-Signal Voltage Gain	V _S = ±15V, V _{OUT} = ±10V R _L ≥ 2k		50			1	25			2,3	V/mV
SR	Slew Rate	V _S = ±15V, A _V = 1	5	50								V/μs
GBW	Gain Bandwidth Product	V _S = ±15V		15								MHz
	Output Voltage Swing	V _S = ±15V, R _L = 2k		±12			4	±12			5,6	V
	Input Voltage Range	V _S = ±20V		±16.5			1	±16.5			2,3	V
I _S	Supply Current					8	1					mA
		T _A = 125°C								7	2	mA
CMRR	Common Mode Rejection Ratio			80			1	80			2,3	dB
PSRR	Power Supply Rejection Ratio			70			1	70			2,3	dB

TABLE 1A: ELECTRICAL CHARACTERISTICS (Postirradiation) (Note 6, 7)

SYMBOL	PARAMETER	CONDITIONS	NOTES	10Krad(Si)		20Krad(Si)		50Krad(Si)		100Krad(Si)		200Krad(Si)		UNITS
				MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
V _{OS}	Input Offset Voltage			4		4		4		4		10		mV
I _{OS}	Input Offset Current			50		50		50		50		100		nA
I _B	Input Bias Current			250		250		250		300		400		nA
R _{IN}	Input Resistance		4	1		1		1		0.5		0.5		MΩ
A _V	Large-Signal Voltage Gain	V _S = ±15V, V _{OUT} = ±10V R _L ≥ 2k		50		50		50		50		25		V/mV
SR	Slew Rate	V _S = ±15V, A _V = 1	5	50		50		50		50		50		V/μs
GBW	Gain Bandwidth Product	V _S = ±15V		15 (Typ)	15 (Typ)	15 (Typ)	15 (Typ)	15 (Typ)	MHz					
	Output Voltage Swing	V _S = ±15V, R _L = 2k		±12		±12		±12		±12		±12		V
	Input Voltage Range			±16.5		±16.5		±16.5		±15		±12		V
I _S	Supply Current			8		8		8		8		8		mA
CMRR	Common Mode Rejection Ratio			80		80		80		80		70		dB
PSRR	Power Supply Rejection Ratio			70		70		70		70		60		dB

ELECTRICAL CHARACTERISTICS (Continued)

Note 1: The inputs are shunted with back-to-back Zeners for overvoltage protection. Excessive current will flow if a differential voltage greater than 5V is applied to the inputs.

Note 2: For supply voltages less than $\pm 15\text{V}$, the maximum input voltage is equal to the supply voltage.

Note 3: These specifications apply for $\pm 5\text{V} \leq V_S \leq \pm 20\text{V}$. The power supplies must be bypassed with a $0.1\mu\text{F}$ or greater disc capacitor within four inches of the device.

Note 4: Guaranteed by design, characterization or correlation to other tested parameters.

Note 5: Slew rate is 100% tested at wafer probe testing. It is QA sample tested in finished package form.

Note 6: $T_A = 25^\circ\text{C}$, $V_S = \pm 20\text{V}$, $V_{CM} = 0\text{V}$, unless otherwise specified. Supply bypassed per Note 3.

Note 7: Device is characterized at 10KRAD, 20KRAD, 50KRAD, 100KRAD and 200KRAD, and is production tested at 100KRAD only.

TOTAL DOSE BIAS CIRCUIT

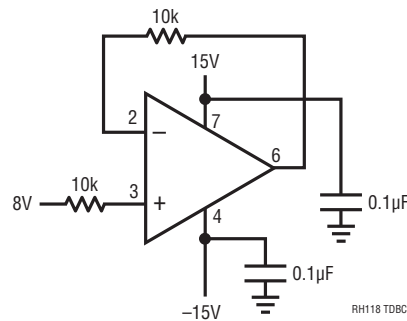


TABLE 2: ELECTRICAL TEST REQUIREMENTS

MIL-PRF-38535 TEST REQUIREMENTS	SUBGROUP
Final Electrical Test Requirements	1*, 2, 3, 4, 5, 6
Group A Test Requirements	1, 2, 3, 4, 5, 6
Group C End Point Electrical Parameters	1, 2, 3
Group D End Point Electrical Parameters	1, 2, 3
Group E End Point Electrical Parameters	1

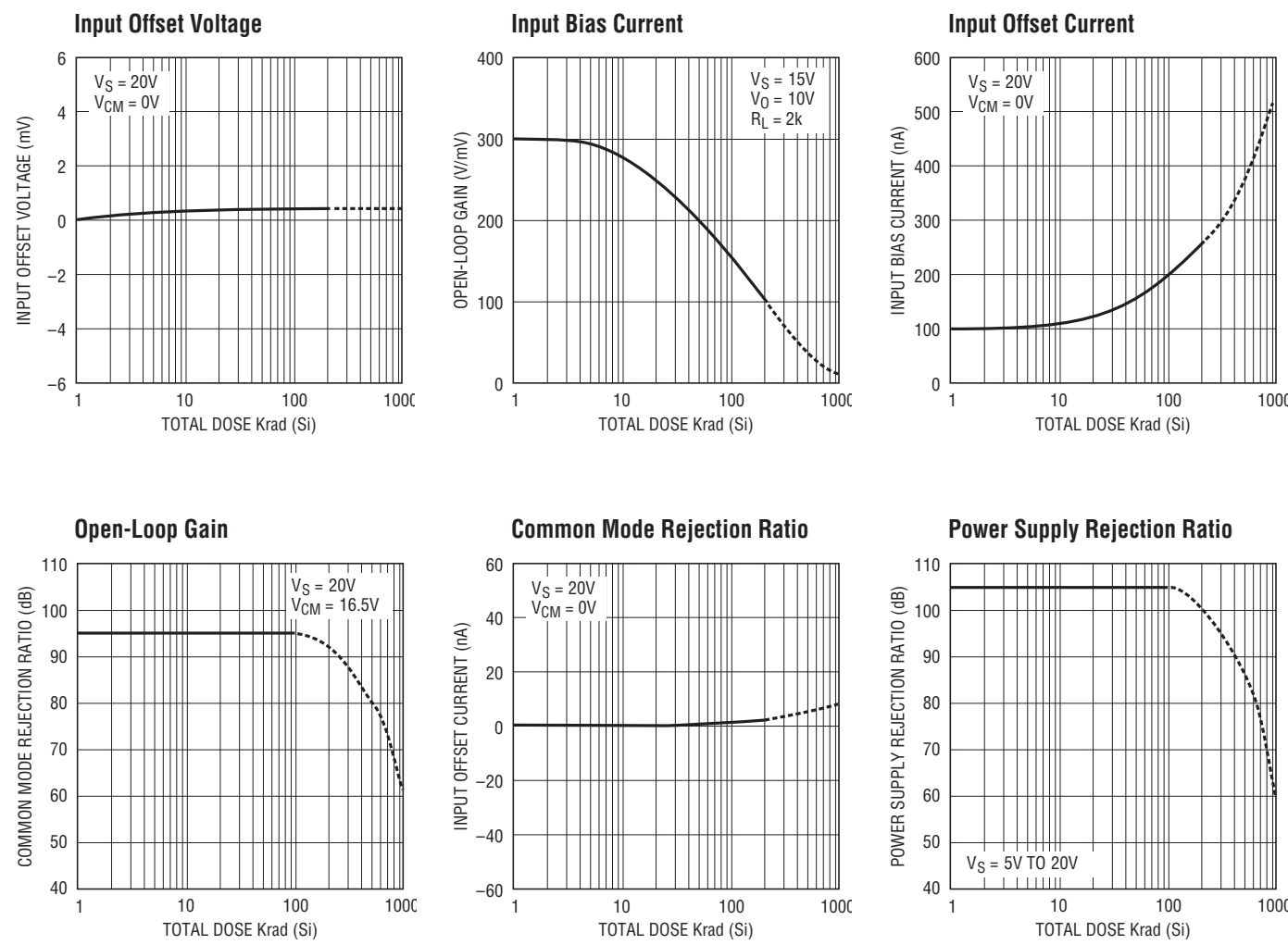
*PDA Applies to subgroup 1. See PDA Test Notes.

PDA Test Notes

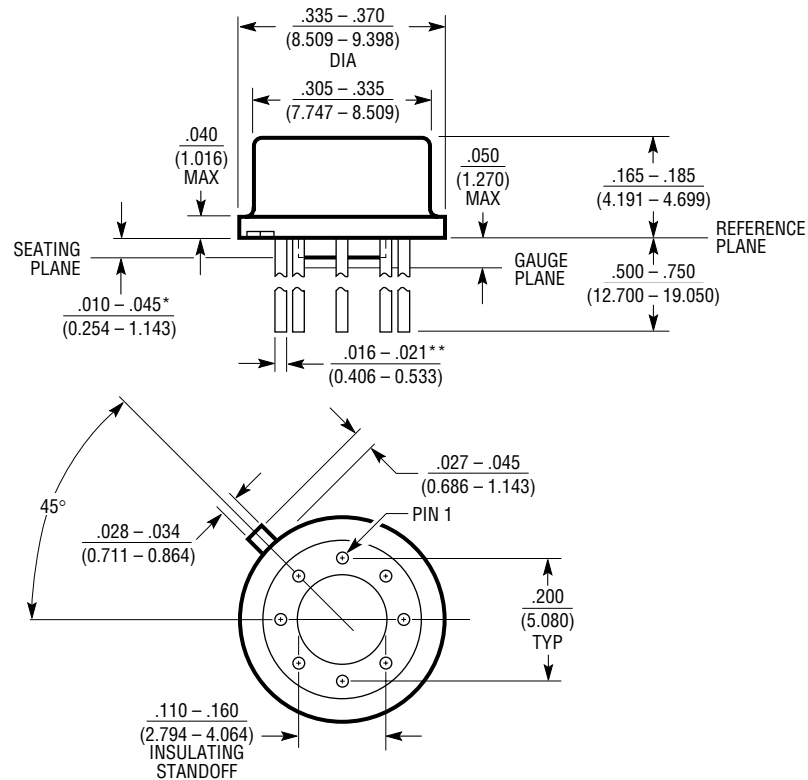
The PDA is specified as 5% based on failures from group A, subgroup 1, tests after cooldown as the final electrical test in accordance with method 5004 of MIL-STD-883 Class B. The verified failures (including Delta parameters) of group A, subgroup 1, after burn-in divided by the total number of devices submitted for burn-in in that lot shall be used to determine the percent for the lot.

Analog Devices reserves the right to test to tighter limits than those given.

TYPICAL PERFORMANCE CHARACTERISTICS



PACKAGE OUTLINE DRAWINGS

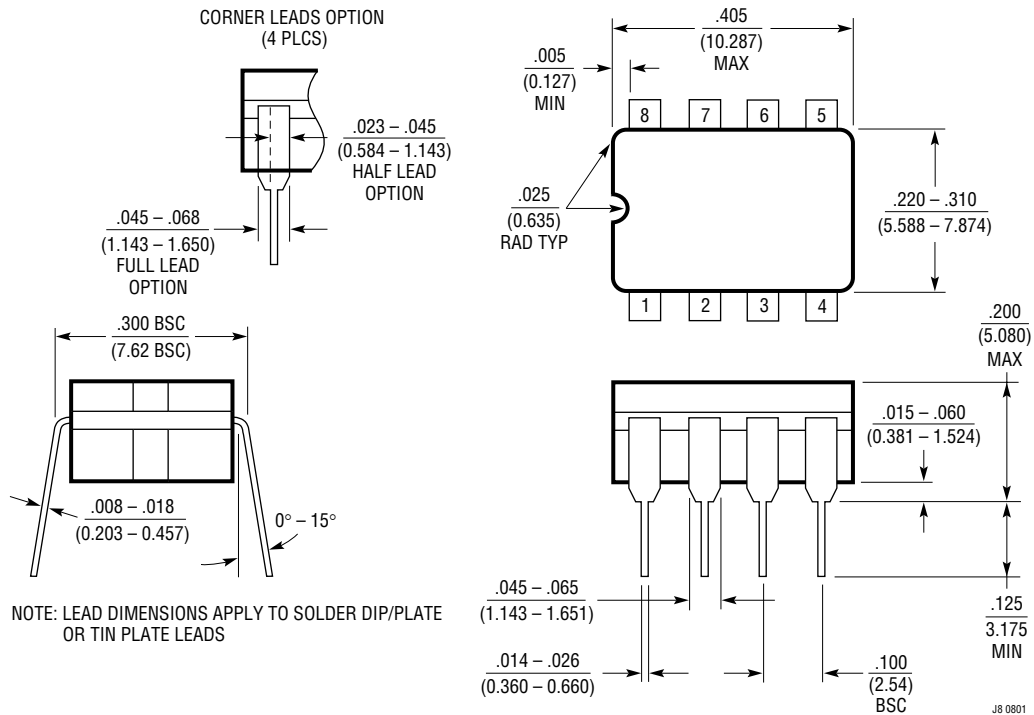


* LEAD DIAMETER IS UNCONTROLLED BETWEEN THE REFERENCE PLANE AND THE SEATING PLANE

** FOR SOLDER DIP LEAD FINISH, LEAD DIAMETER IS $.016 - .024$ (0.406 - 0.610) H8(TO-5) 0.200 PCD 0204

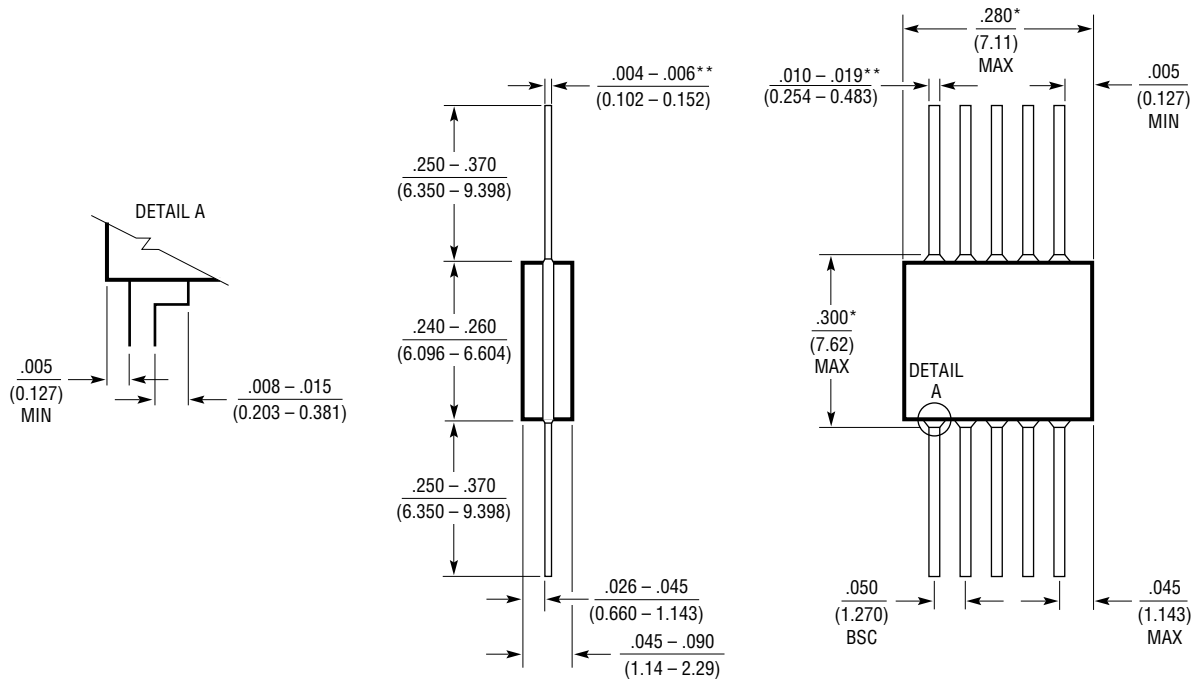
H Package
8-Lead TO-5 Metal Can (.200 Inch PCD)
(Reference LTC DWG # 05-08-1320)

PACKAGE OUTLINE DRAWINGS



J8 Package
8-Lead CERDIP (Narrow .300 Inch, Hermetic)
(Reference LTC DWG # 05-08-1110)

PACKAGE OUTLINE DRAWINGS



NOTES:

*THIS DIMENSION ALLOWS FOR OFF-CENTER LID, MENISCUS AND GLASS OVERRUN

**INCREASE DIMENSIONS BY 0.003 INCHES (0.076 mm) WHEN LEAD FINISH A IS APPLIED (SOLDER DIPPED)

W10 (GLASS) 0603

W Package 10-Lead Flatpak Glass Sealed (Hermetic) (Reference LTC DWG # 05-08-1130)

REVISION HISTORY

REV	DATE	DESCRIPTION	PAGE NUMBER
C	04/19	Obsolete H + J Package and updating to ADI format	1-4
D	07/23	Updated art title in the Electrical Characteristics section	2
E	06/24	Changes Electrical Test Requirements, Table 2	3
F	07/25	Changes to Table 1A: Electrical Characteristics Added Package Outline Drawings	2-3 5-7